74HC4066-Q100; 74HCT4066-Q100

Quad single-pole single-throw analog switch

Rev. 5 — 21 March 2024 Product data sheet

1. General description

The 74HC4066-Q100; 74HCT4066-Q100 is a quad single pole, single throw analog switch. Each switch features two input/output terminals (nY and nZ) and an active HIGH enable input (nE). When nE is LOW, the analog switch is turned off. Inputs include clamp diodes. This enables the use of current limiting resistors to interface inputs to voltages in excess of V_{CC}.

This product has been qualified to the Automotive Electronics Council (AEC) standard Q100 (Grade 1) and is suitable for use in automotive applications.

2. Features and benefits

- Automotive product qualification in accordance with AEC-Q100 (Grade 1)
  - Specified from -40 °C to +85 °C and from -40 °C to +125 °C
- Input levels nE inputs:
  - For 74HC4066-Q100: CMOS level
  - For 74HCT4066-Q100: TTL level
- Low ON resistance:
  - 50 Ω (typical) at V_{CC} = 4.5 V
  - 45 Ω (typical) at V_{CC} = 6.0 V
  - 35 Ω (typical) at V_{CC} = 9.0 V
- Specified in compliance with JEDEC standard no. 7A
- ESD protection:
  - HBM: ANSI/ESDA/JEDEC JS-001 class 2 exceeds 2000 V
  - CDM: ANSI/ESDA/JEDEC JS-002 class C3 exceeds 1000 V
- Multiple package options
- DHVQFN package with Side-Wettable Flanks enabling Automatic Optical Inspection (AOI) of solder joints

3. Ordering information

Table 1. Ordering information

Type number	Package			
	Temperature range	Name	Description	Version
74HC4066D-Q100	-40 °C to +125 °C	SO14	plastic small outline package; 14 leads; body width 3.9 mm	SOT108-1
74HCT4066D-Q100				
74HC4066PW-Q100	-40 °C to +125 °C	TSSOP14	plastic thin shrink small outline package; 14 leads; body width 4.4 mm	SOT402-1
74HCT4066PW-Q100				
74HC4066BQ-Q100	-40 °C to +125 °C	DHVQFN14	plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 14 terminals; body 2.5 × 3 × 0.85 mm	SOT762-1
74HCT4066BQ-Q100				

4. Functional diagram

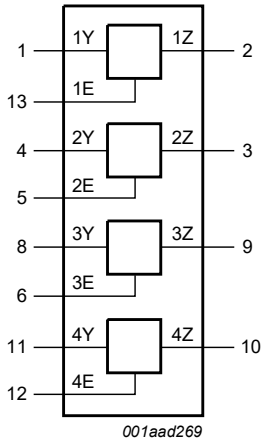


Fig. 1. Logic symbol

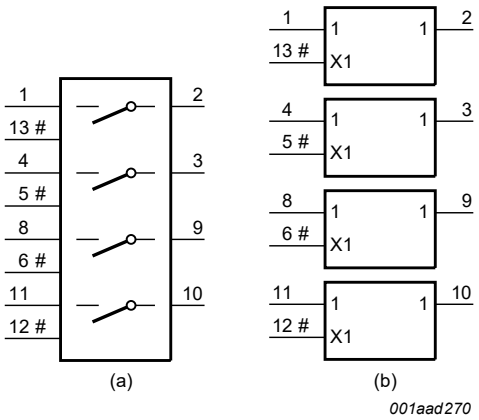


Fig. 2. IEC logic symbol

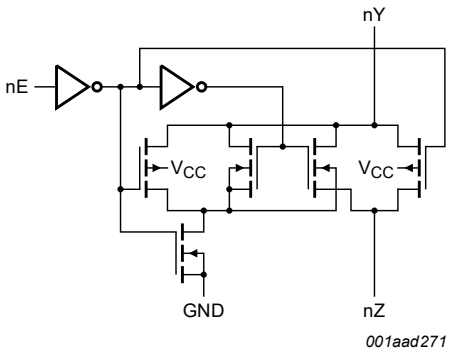


Fig. 3. Schematic diagram (one switch)

5. Pinning information

5.1. Pinning

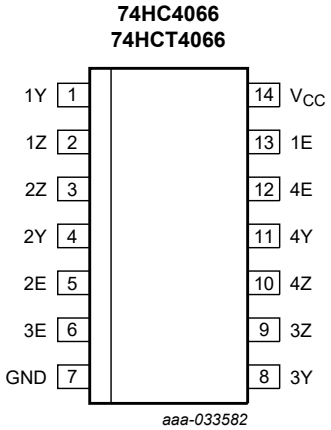


Fig. 4. Pin configuration SOT108-1 (SO14)

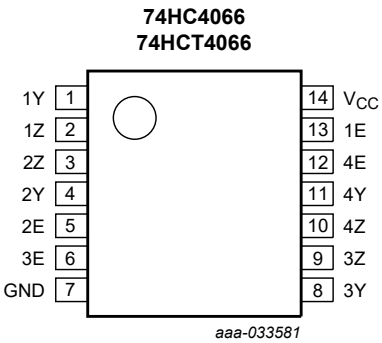
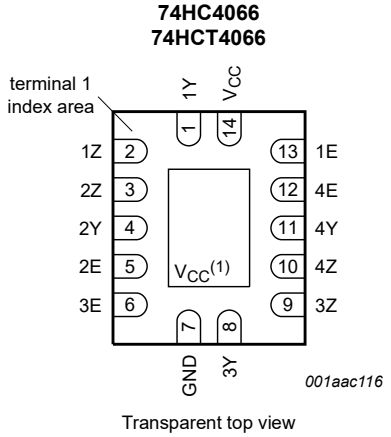


Fig. 5. Pin configuration and SOT402-1 (TSSOP14)



Transparent top view

(1) This is not a supply pin. There is no electrical or mechanical requirement to solder the pad. In case soldered, the solder land should remain floating or connected to V_{CC}

Fig. 6. Pin configuration SOT762-1 (DHVQFN14)

5.2. Pin description

Table 2. Pin description

Symbol	Pin	Description
1Z, 2Z, 3Z, 4Z	2, 3, 9, 10	independent input or output
1Y, 2Y, 3Y, 4Y	1, 4, 8, 11	independent input or output
GND	7	ground (0 V)
1E, 2E, 3E, 4E	13, 5, 6, 12	enable input (active HIGH)
V_{CC}	14	supply voltage

6. Functional description

Table 3. Function table

H = HIGH voltage level; L = LOW voltage level.

Input nE	Switch
L	OFF
H	ON

7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions		Min	Max	Unit
V_{CC}	supply voltage			-0.5	+11.0	V
I_{IK}	input clamping current	$V_I < -0.5$ V or $V_I > V_{CC} + 0.5$ V		-	±20	mA
I_{SK}	switch clamping current	$V_{SW} < -0.5$ V or $V_{SW} > V_{CC} + 0.5$ V		-	±20	mA
I_{SW}	switch current	V_{SW} = -0.5 V to V_{CC} + 0.5 V	[1]	-	±25	mA
I_{CC}	supply current			-	50	mA
I_{GND}	ground current			-	-50	mA
T_{stg}	storage temperature			-65	+150	°C
P_{tot}	total power dissipation	T_{amb} = -40 °C to +125 °C	[2]	-	500	mW
P	power dissipation	per switch		-	100	mW

[1] To avoid drawing V_{CC} current out of terminal Z, when switch current flows in terminals Yn, the voltage drop across the bidirectional switch must not exceed 0.4 V. If the switch current flows into terminal Z, no V_{CC} current will flow out of terminals Yn. In this case there is no limit for the voltage drop across the switch, but the voltages at Yn and Z may not exceed V_{CC} or GND.

[2] For SOT108-1 (SO14) package: P_{tot} derates linearly with 10.1 mW/K above 100 °C.
For SOT402-1 (TSSOP14) package: P_{tot} derates linearly with 7.3 mW/K above 81 °C.
For SOT762-1 (DHVQFN14) package: P_{tot} derates linearly with 9.6 mW/K above 98 °C.

8. Recommended operating conditions

Table 5. Recommended operating conditions

Symbol	Parameter	Conditions	74HC4066-Q100			74HCT4066-Q100			Unit
			Min	Typ	Max	Min	Typ	Max	
V_{CC}	supply voltage		2.0	5.0	10.0	4.5	5.0	5.5	V
V_I	input voltage		GND	-	V_{CC}	GND	-	V_{CC}	V
V_{SW}	switch voltage		GND	-	V_{CC}	GND	-	V_{CC}	V
T_{amb}	ambient temperature		-40	+25	+125	-40	+25	+125	°C
Δt/ΔV	input transition rise and fall rate	V_{CC} = 2.0 V	-	-	625	-	-	-	ns/V
		V_{CC} = 4.5 V	-	1.67	139	-	1.67	139	ns/V
		V_{CC} = 6.0 V	-	-	83	-	-	-	ns/V
		V_{CC} = 10.0 V	-	-	35	-	-	-	ns/V

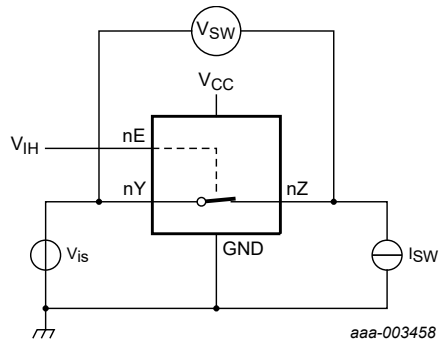
9. Static characteristics

Table 6. R_{ON} resistance per switch for types 74HC4066-Q100 and 74HCT4066-Q100

V_I = V_{IH} or V_{IL}; for test circuit see Fig. 7.
V_{is} is the input voltage at a Yn or Z terminal, whichever is assigned as an input.
V_{os} is the output voltage at a Yn or Z terminal, whichever is assigned as an output.
For 74HC4066-Q100: V_{CC} - GND = 2.0 V, 4.5 V, 6.0 V and 9.0 V.
For 74HCT4066-Q100: V_{CC} - GND = 4.5 V.

Symbol	Parameter	Conditions	-40 °C to +85 °C			-40 °C to +125 °C		Unit
			Min	Typ[1]	Max	Min	Max	
$R_{ON(peak)}$	ON resistance (peak)	V_{is} = V_{CC} to GND						
		V_{CC} = 2.0 V; I_{SW} = 100 µA [2]	-	-	-	-	-	Ω
		V_{CC} = 4.5 V; I_{SW} = 1000 µA	-	54	-	118	142	Ω
		V_{CC} = 6.0 V; I_{SW} = 1000 µA	-	42	-	105	126	Ω
		V_{CC} = 9.0 V; I_{SW} = 1000 µA	-	32	-	88	105	Ω
$R_{ON(rail)}$	ON resistance (rail)	V_{is} = GND						
		V_{CC} = 2.0 V; I_{SW} = 100 µA [2]	-	80	-	-	-	Ω
		V_{CC} = 4.5 V; I_{SW} = 1000 µA	-	35	-	95	115	Ω
		V_{CC} = 6.0 V; I_{SW} = 1000 µA	-	27	-	82	100	Ω
		V_{CC} = 9.0 V; I_{SW} = 1000 µA	-	20	-	70	85	Ω
		V_{is} = V_{CC}						
		V_{CC} = 2.0 V; I_{SW} = 100 µA [2]	-	100	-	-	-	Ω
		V_{CC} = 4.5 V; I_{SW} = 1000 µA	-	42	-	106	128	Ω
		V_{CC} = 6.0 V; I_{SW} = 1000 µA	-	35	-	94	113	Ω
		V_{CC} = 9.0 V; I_{SW} = 1000 µA	-	20	-	78	95	Ω
ΔR_{ON}	ON resistance mismatch between channels	V_{is} = V_{CC} to GND						
		V_{CC} = 2.0 V [2]	-	-	-	-	-	Ω
		V_{CC} = 4.5 V	-	5	-	-	-	Ω
		V_{CC} = 6.0 V	-	4	-	-	-	Ω
		V_{CC} = 9.0 V	-	3	-	-	-	Ω

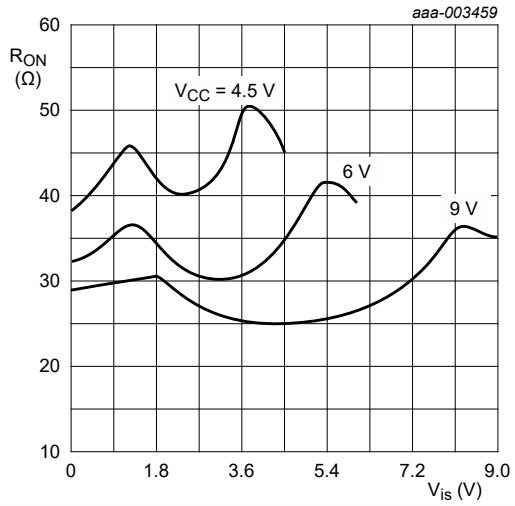
[1] Typical values are measured at T_{amb} = 25 °C.
[2] At supply voltages (V_{CC} - GND) approaching 2 V, the analog switch ON resistance becomes extremely non-linear. Therefore it is recommended that these devices be used to transmit digital signals only, when using these supply voltages.



V_{is} = 0 V to V_{CC}

$$R_{ON} = \frac{V_{SW}}{I_{SW}}$$

Fig. 7. Test circuit for measuring R_{ON}



V_{is} = 0 V to V_{CC}

Fig. 8. Typical R_{ON} as a function of input voltage V_{is}

Table 7. Static characteristics 74HC4066-Q100

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).
V_{is} is the input voltage at a Yn or Z terminal, whichever is assigned as an input.
V_{os} is the output voltage at a Yn or Z terminal, whichever is assigned as an output.

Symbol	Parameter	Conditions	Min	Typ[1]	Max	Unit
T_{amb} = -40 °C to +85 °C						
V_{IH}	HIGH-level input voltage	V_{CC} = 2.0 V	1.5	1.2	-	V
		V_{CC} = 4.5 V	3.15	2.4	-	V
		V_{CC} = 6.0 V	4.2	3.2	-	V
		V_{CC} = 9.0 V	6.3	4.7	-	V
V_{IL}	LOW-level input voltage	V_{CC} = 2.0 V	-	0.8	0.5	V
		V_{CC} = 4.5 V	-	2.1	1.35	V
		V_{CC} = 6.0 V	-	2.8	1.80	V
		V_{CC} = 9.0 V	-	4.3	2.70	V
I_I	input leakage current	V_I = V_{CC} or GND				
		V_{CC} = 6.0 V	-	-	±1.0	µA
		V_{CC} = 10.0 V	-	-	±2.0	µA
$I_{S(OFF)}$	OFF-state leakage current	V_{CC} = 10.0 V; V_I = V_{IH} or V_{IL}; $\|V_{SW}\|$ = V_{CC} - GND; see Fig. 9				
		per channel	-	-	±1.0	µA
$I_{S(ON)}$	ON-state leakage current	V_{CC} = 10.0 V; V_I = V_{IH} or V_{IL}; $\|V_{SW}\|$ = V_{CC} - GND; see Fig. 10	-	-	±1.0	µA
I_{CC}	supply current	V_I = V_{CC} or GND; V_{is} = GND or V_{CC}; V_{os} = V_{CC} or GND				
		V_{CC} = 6.0 V	-	-	20.0	µA
		V_{CC} = 10.0 V	-	-	40.0	µA
C_I	input capacitance		-	3.5	-	pF
C_{sw}	switch capacitance		-	8	-	pF

Symbol	Parameter	Conditions	Min	Typ[1]	Max	Unit
T_{amb} = -40 °C to +125 °C						
V_{IH}	HIGH-level input voltage	V_{CC} = 2.0 V	1.5	-	-	V
		V_{CC} = 4.5 V	3.15	-	-	V
		V_{CC} = 6.0 V	4.2	-	-	V
		V_{CC} = 9.0 V	6.3	-	-	V
V_{IL}	LOW-level input voltage	V_{CC} = 2.0 V	-	-	0.50	V
		V_{CC} = 4.5 V	-	-	1.35	V
		V_{CC} = 6.0 V	-	-	1.80	V
		V_{CC} = 9.0 V	-	-	2.70	V
I_I	input leakage current	V_I = V_{CC} or GND				
		V_{CC} = 6.0 V	-	-	±1.0	µA
		V_{CC} = 10.0 V	-	-	±2.0	µA
$I_{S(OFF)}$	OFF-state leakage current	V_{CC} = 10.0 V; V_I = V_{IH} or V_{IL}; $\lvert V_{SW}\rvert$ = V_{CC} - GND; see Fig. 9				
		per channel	-	-	±1.0	µA
$I_{S(ON)}$	ON-state leakage current	V_{CC} = 10.0 V; V_I = V_{IH} or V_{IL}; $\lvert V_{SW}\rvert$ = V_{CC} - GND; see Fig. 10	-	-	±1.0	µA
I_{CC}	supply current	V_I = V_{CC} or GND; V_{is} = GND or V_{CC}; V_{os} = V_{CC} or GND				
		V_{CC} = 6.0 V	-	-	40	µA
		V_{CC} = 10.0 V	-	-	80	µA

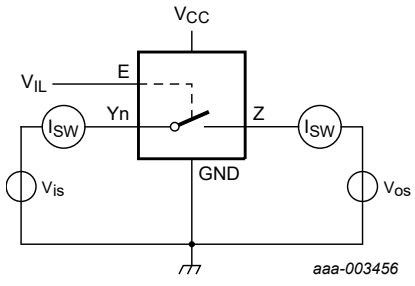
[1] Typical values are measured at T_{amb} = 25 °C.

Table 8. Static characteristics 74HCT4066-Q100

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).
V_{is} is the input voltage at a Yn or Z terminal, whichever is assigned as an input.
V_{os} is the output voltage at a Yn or Z terminal, whichever is assigned as an output.

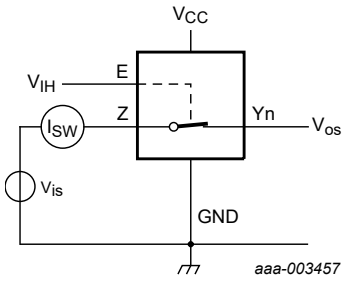
Symbol	Parameter	Conditions	Min	Typ[1]	Max	Unit
T_{amb} = -40 °C to +85 °C						
V_{IH}	HIGH-level input voltage	V_{CC} = 4.5 V to 5.5 V	2.0	1.6	-	V
V_{IL}	LOW-level input voltage	V_{CC} = 4.5 V to 5.5 V	-	1.2	0.8	V
I_I	input leakage current	V_I = V_{CC} or GND; V_{CC} = 5.5 V	-	-	±1.0	µA
$I_{S(OFF)}$	OFF-state leakage current	V_{CC} = 5.5 V; V_I = V_{IH} or V_{IL}; $\|V_{SW}\|$ = V_{CC} - GND; see Fig. 9				
		per channel	-	-	±1.0	µA
$I_{S(ON)}$	ON-state leakage current	V_{CC} = 5.5 V; V_I = V_{IH} or V_{IL}; $\|V_{SW}\|$ = V_{CC} - GND; see Fig. 10	-	-	±1.0	µA
I_{CC}	supply current	V_I = V_{CC} or GND; V_{is} = GND or V_{CC}; V_{os} = V_{CC} or GND; V_{CC} = 4.5 V to 5.5 V	-	-	20.0	µA
ΔI_{CC}	additional supply current	per input pin; V_I = V_{CC} - 2.1 V; other inputs at V_{CC} or GND; V_{CC} = 4.5 V to 5.5 V	-	100	450	µA
C_I	input capacitance		-	3.5	-	pF
C_{sw}	switch capacitance		-	8	-	pF
T_{amb} = -40 °C to +125 °C						
V_{IH}	HIGH-level input voltage	V_{CC} = 4.5 V to 5.5 V	2.0	-	-	V
V_{IL}	LOW-level input voltage	V_{CC} = 4.5 V to 5.5 V	-	-	0.8	V
I_I	input leakage current	V_I = V_{CC} or GND; V_{CC} = 5.5 V	-	-	±1.0	µA
$I_{S(OFF)}$	OFF-state leakage current	V_{CC} = 5.5 V; V_I = V_{IH} or V_{IL}; $\|V_{SW}\|$ = V_{CC} - GND; see Fig. 9				
		per channel	-	-	±1.0	µA
$I_{S(ON)}$	ON-state leakage current	V_{CC} = 5.5 V; V_I = V_{IH} or V_{IL}; $\|V_{SW}\|$ = V_{CC} - GND; see Fig. 10	-	-	±1.0	µA
I_{CC}	supply current	V_I = V_{CC} or GND; V_{is} = GND or V_{CC}; V_{os} = V_{CC} or GND; V_{CC} = 4.5 V to 5.5 V	-	-	40	µA
ΔI_{CC}	additional supply current	per input pin; V_I = V_{CC} - 2.1 V; other inputs at V_{CC} or GND; V_{CC} = 4.5 V to 5.5 V	-	-	490	µA

[1] Typical values are measured at T_{amb} = 25 °C.



V_{is} = V_{CC} and V_{os} = GND
V_{is} = GND and V_{os} = V_{CC}

Fig. 9. Test circuit for measuring OFF-state leakage current



V_{is} = V_{CC} and V_{os} = open
V_{is} = GND and V_{os} = open

Fig. 10. Test circuit for measuring ON-state leakage current

10. Dynamic characteristics

Table 9. Dynamic characteristics 74HC4066-Q100

GND = 0 V; $t_r = t_f$ = 6 ns; C_L = 50 pF unless specified otherwise; for test circuit see Fig. 13.
V_{is} is the input voltage at a Yn or Z terminal, whichever is assigned as an input.
V_{os} is the output voltage at a Yn or Z terminal, whichever is assigned as an output.

Symbol	Parameter	Conditions	-40 °C to +85 °C			-40 °C to +125 °C		Unit
			Min	Typ[1]	Max	Min	Max	
t_{pd}	propagation delay	nY to nZ or nZ to nY; R_L = ∞ Ω; see Fig. 11 [2]						
		V_{CC} = 2.0 V	-	8	75	-	90	ns
		V_{CC} = 4.5 V	-	3	15	-	18	ns
		V_{CC} = 6.0 V	-	2	13	-	15	ns
		V_{CC} = 9.0 V	-	2	10	-	12	ns
t_{off}	turn-off time	nE to nY or nZ; see Fig. 12 [3]						
		V_{CC} = 2.0 V	-	44	190	-	225	ns
		V_{CC} = 4.5 V	-	16	38	-	45	ns
		V_{CC} = 5.0 V; C_L = 15 pF	-	13	-	-	-	ns
		V_{CC} = 6.0 V	-	13	33	-	38	ns
		V_{CC} = 9.0 V	-	16	26	-	30	ns
t_{on}	turn-on time	nE to nY or nZ; see Fig. 12 [4]						
		V_{CC} = 2.0 V	-	36	125	-	150	ns
		V_{CC} = 4.5 V	-	13	25	-	30	ns
		V_{CC} = 5.0 V; C_L = 15 pF	-	11	-	-	-	ns
		V_{CC} = 6.0 V	-	10	21	-	26	ns
		V_{CC} = 9.0 V	-	8	16	-	20	ns
C_{PD}	power dissipation capacitance	per switch; V_I = GND to V_{CC} [5]	-	11	-	-	-	pF

[1] Typical values are measured at T_{amb} = 25 °C.
[2] t_{pd} is the same as t_{PHL} and t_{PLH}.
[3] t_{off} is the same as t_{PZH} and t_{PZL}.
[4] t_{on} is the same as t_{PHZ} and t_{PLZ}.
[5] C_{PD} is used to determine the dynamic power dissipation (P_D in µW).
$P_D = C_{PD} \times V_{CC}^2 \times f_i + \sum\{(C_L + C_{sw}) \times V_{CC}^2 \times f_o\}$ where:
f_i = input frequency in MHz;
f_o = output frequency in MHz;
$\sum\{(C_L + C_{sw}) \times V_{CC}^2 \times f_o\}$ = sum of outputs;
C_L = output load capacitance in pF;
C_{sw} = switch capacitance in pF;
V_{CC} = supply voltage in V.

Table 10. Dynamic characteristics 74HCT4066-Q100

GND = 0 V; $t_r = t_f$ = 6 ns; C_L = 50 pF unless specified otherwise; for test circuit see Fig. 13.
V_{is} is the input voltage at a Yn or Z terminal, whichever is assigned as an input.
V_{os} is the output voltage at a Yn or Z terminal, whichever is assigned as an output.

Symbol	Parameter	Conditions	-40 °C to +85 °C			-40 °C to +125 °C		Unit
			Min	Typ[1]	Max	Min	Max	
t_{pd}	propagation delay	nY to nZ or nZ to nY; R_L = ∞ Ω; see Fig. 11 [2]						
		V_{CC} = 4.5 V	-	3	15	-	18	ns
t_{off}	turn-off time	nE to nY or nZ; see Fig. 12 [3]						
		V_{CC} = 4.5 V	-	20	44	-	53	ns
		V_{CC} = 5.0 V; C_L = 15 pF	-	16	-	-	-	ns
t_{on}	turn-on time	nE to nY or nZ; see Fig. 12 [4]						
		V_{CC} = 4.5 V	-	12	30	-	36	ns
		V_{CC} = 5.0 V; C_L = 15 pF	-	12	-	-	-	ns
C_{PD}	power dissipation capacitance	per switch; V_I = GND to (V_{CC} - 1.5 V) [5]	-	12	-	-	-	pF

[1] Typical values are measured at T_{amb} = 25 °C.
[2] t_{pd} is the same as t_{PHL} and t_{PLH}.
[3] t_{off} is the same as t_{PZH} and t_{PZL}.
[4] t_{on} is the same as t_{PHZ} and t_{PLZ}.
[5] C_{PD} is used to determine the dynamic power dissipation (P_D in µW).
$P_D = C_{PD} \times V_{CC}^2 \times f_i + \sum\{(C_L + C_{sw}) \times V_{CC}^2 \times f_o\}$ where:
f_i = input frequency in MHz;
f_o = output frequency in MHz;
$\sum\{(C_L + C_{sw}) \times V_{CC}^2 \times f_o\}$ = sum of outputs;
C_L = output load capacitance in pF;
C_{sw} = switch capacitance in pF;
V_{CC} = supply voltage in V.

10.1. Waveforms and test circuit

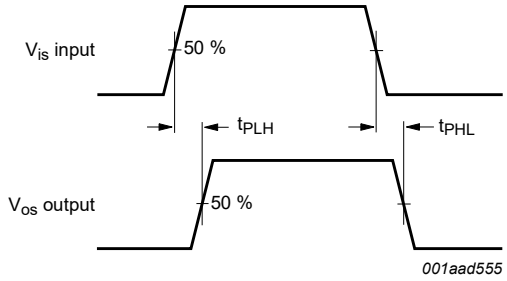
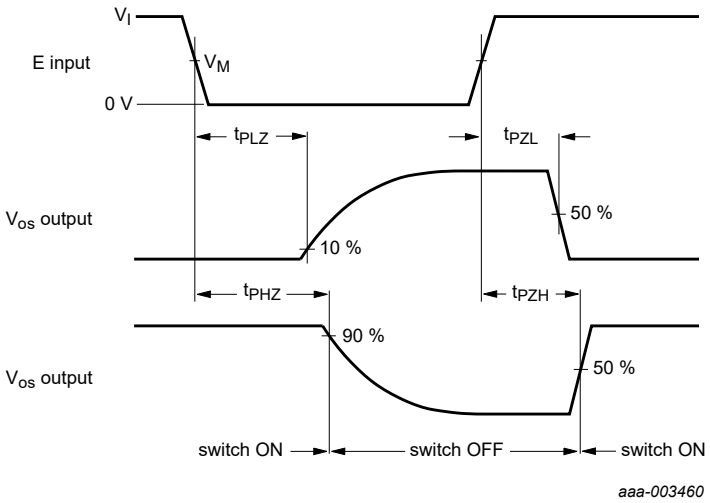


Fig. 11. Input (V_{is}) to output (V_{os}) propagation delays

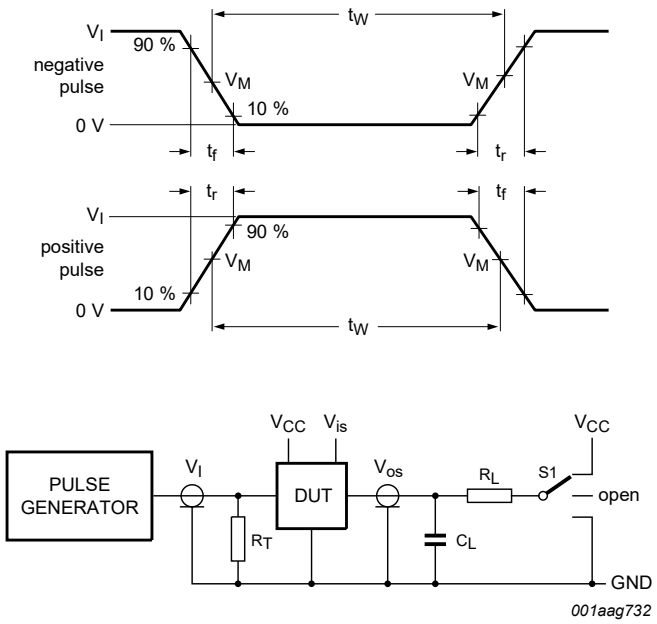


Measurement points are shown in Table 11.

Fig. 12. Turn-on and turn-off times

Table 11. Measurement points

Type	V_I	V_M
74HC4066-Q100	V_{CC}	$0.5V_{CC}$
74HCT4066-Q100	3.0 V	1.3 V



Test data is given in Table 12.

Definitions test circuit:

R_T = Termination resistance should be equal to output impedance Z_o of the pulse generator.

C_L = Load capacitance including jig and probe capacitance.

R_L = Load resistance.

S1 = Test selection switch.

Fig. 13. Test circuit for measuring switching times

Table 12. Test data

Test	Input			Output		S1 position
	Control E	Switch Yn (Z)	t_r, t_f	Switch Z (Yn)		
	V_I [1]	V_{is}		C_L	R_L	
t_{PHL}, t_{PLH}	GND	GND to V_{CC}	6 ns	50 pF	-	open
t_{PHZ}, t_{PZH}	GND to V_{CC}	V_{CC}	6 ns	50 pF, 15 pF	1 kΩ	GND
t_{PLZ}, t_{PZL}	GND to V_{CC}	GND	6 ns	50 pF, 15 pF	1 kΩ	V_{CC}

[1] For 74HCT4066-Q100: maximum input voltage V_I = 3.0 V.

11. Additional dynamic characteristics

Table 13. Additional dynamic characteristics

Recommended conditions and typical values; GND = 0 V; T_{amb} = 25 °C.

V_{is} is the input voltage at a Yn or Z terminal, whichever is assigned as an input.

V_{os} is the output voltage at a Yn or Z terminal, whichever is assigned as an output.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
THD	total harmonic distortion	f_i = 1 kHz; R_L = 10 kΩ; C_L = 50 pF; see Fig. 14				%
		V_{CC} = 4.5 V; V_I = 4.0 V (p-p)	-	0.04	-	%
		V_{CC} = 9.0 V; V_I = 8.0 V (p-p)	-	0.02	-	%
		f_i = 10 kHz; R_L = 10 kΩ; C_L = 50 pF; see Fig. 14				
		V_{CC} = 4.5 V; V_I = 4.0 V (p-p)	-	0.12	-	%
		V_{CC} = 9.0 V; V_I = 8.0 V (p-p)	-	0.06	-	%
$f_{(-3dB)}$	-3 dB frequency response	R_L = 50 Ω; C_L = 10 pF; see Fig. 15 [1]				
		V_{CC} = 4.5 V	-	180	-	MHz
		V_{CC} = 9.0 V	-	200	-	MHz
α_{iso}	isolation (OFF-state)	R_L = 600 Ω; C_L = 50 pF; f_i = 1 MHz; see Fig. 16 [2]				
		V_{CC} = 4.5 V	-	-50	-	dB
		V_{CC} = 9.0 V	-	-50	-	dB
V_{ct}	crosstalk voltage	between digital input and switch (peak to peak value); R_L = 600 Ω; C_L = 50 pF; f_i = 1 MHz; see Fig. 17				
		V_{CC} = 4.5 V	-	110	-	mV
		V_{CC} = 9.0 V	-	220	-	mV
Xtalk	crosstalk	between switches; R_L = 600 Ω; C_L = 50 pF; f_i = 1 MHz; see Fig. 18 [2]				
		V_{CC} = 4.5 V	-	-60	-	dB
		V_{CC} = 9.0 V	-	-60	-	dB

[1] Adjust input voltage V_{is} to 0 dBm level at V_{os} for f_i = 1 MHz (0 dBm = 1 mW into 50 Ω). After set-up, f_i is increased to obtain a reading of -3 dB at V_{os}.

[2] Adjust input voltage V_{is} to 0 dBm level (0 dBm = 1 mW into 600 Ω).

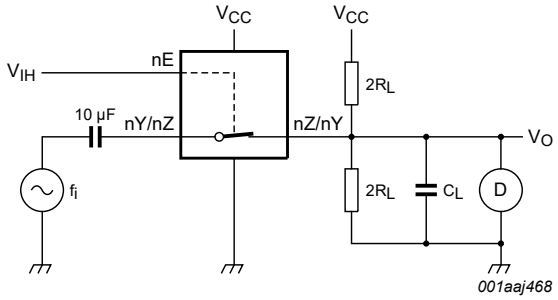
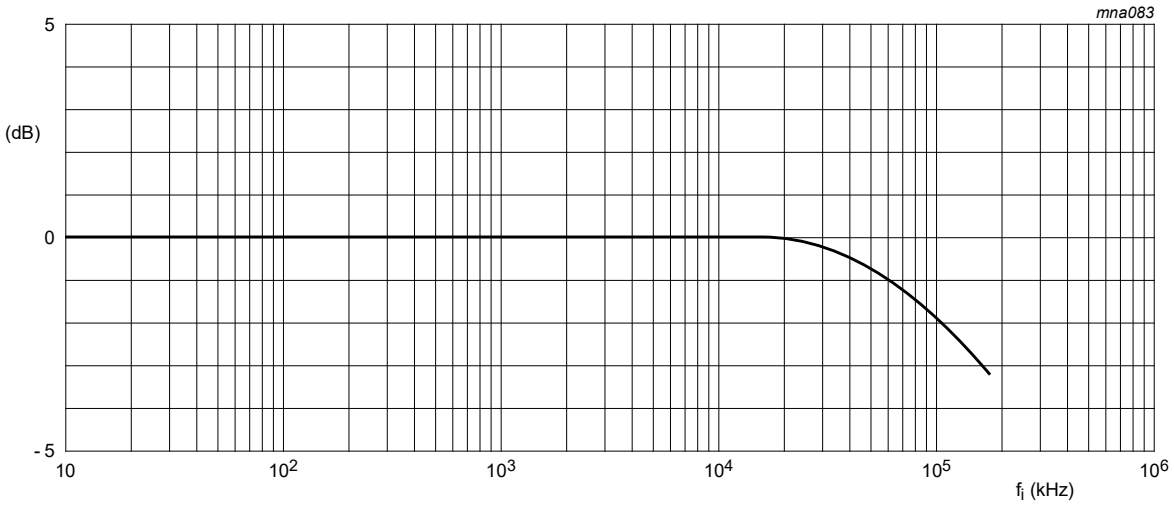
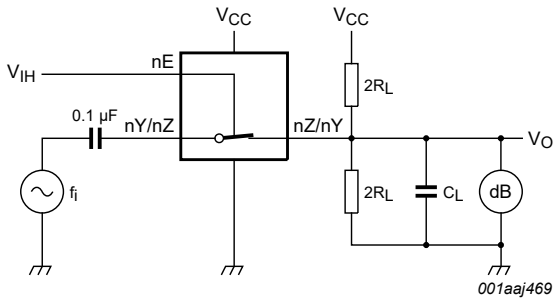


Fig. 14. Test circuit for measuring total harmonic distortion



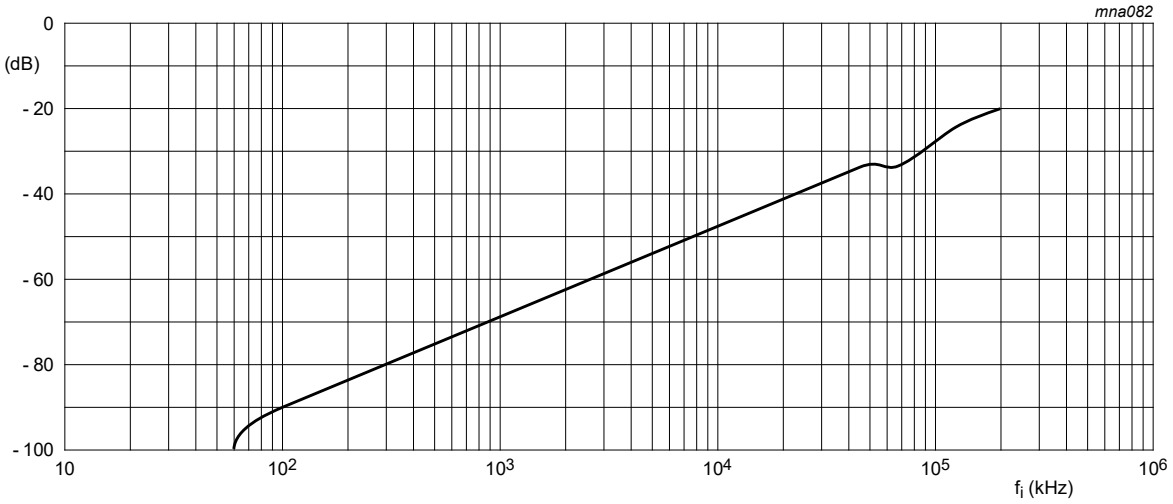
a. Typical -3 dB frequency response



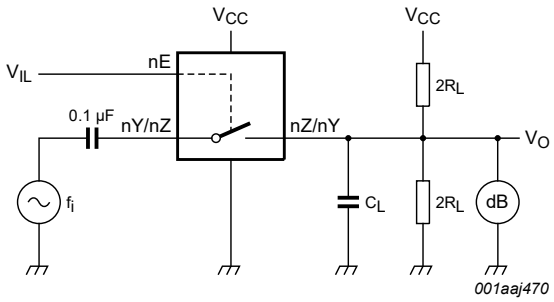
b. Test circuit

V_{CC} = 4.5 V; GND = 0 V; R_L = 50 Ω; R_{source} = 1 kΩ.

Fig. 15. -3 dB frequency response as a function of frequency



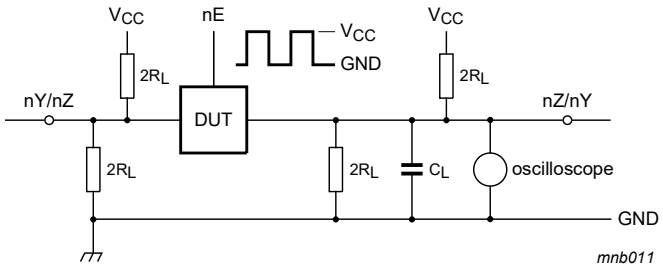
a. Isolation (OFF-state)



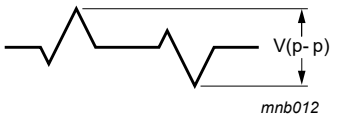
b. Test circuit

V_{CC} = 4.5 V; GND = 0 V; R_L = 600 Ω; R_{source} = 1 kΩ.

Fig. 16. Isolation (OFF-state) as a function of frequency



a. Test circuit



b. Crosstalk voltage

Fig. 17. Test circuit for measuring crosstalk voltage (between the digital input and the switch)

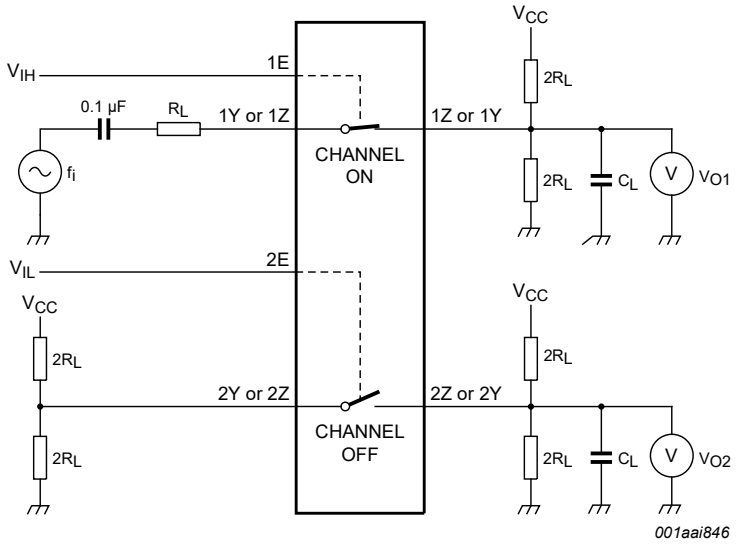
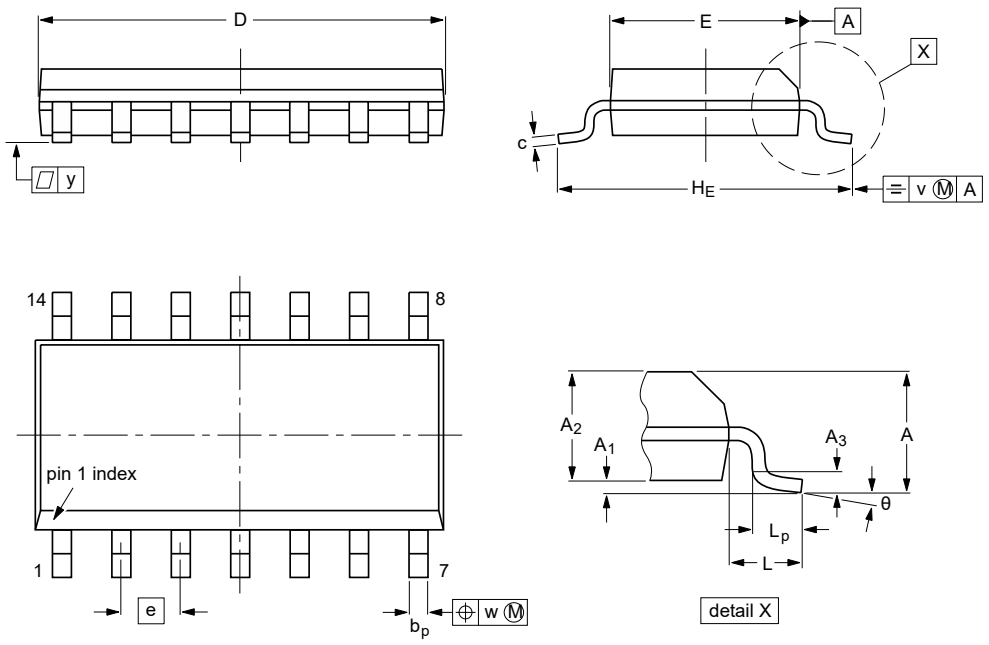


Fig. 18. Test circuit for measuring crosstalk (between the switches)

12. Package outline

SO14: plastic small outline package; 14 leads; body width 3.9 mm **SOT108-1**



Dimensions (inch dimensions are derived from the original mm dimensions)

Unit		A	A_1	A_2	A_3	b_p	c	$D^{(1)}$	$E^{(1)}$	e	H_E	L	L_p	v	w	y	θ
mm	max	1.75	0.25			0.51	0.25	8.75	4.0		6.2		1.27				8°
	nom				0.25					1.27		1.05		0.2	0.25	0.1	
	min		0.10	1.25		0.31	0.10	8.55	3.8		5.8		0.4				0°
inches	max	0.069	0.010			0.020	0.010	0.344	0.16		0.244		0.05				8°
	nom				0.01					0.05		0.041		0.008	0.01	0.004	
	min		0.004	0.049		0.012	0.004	0.337	0.15		0.228		0.016				0°

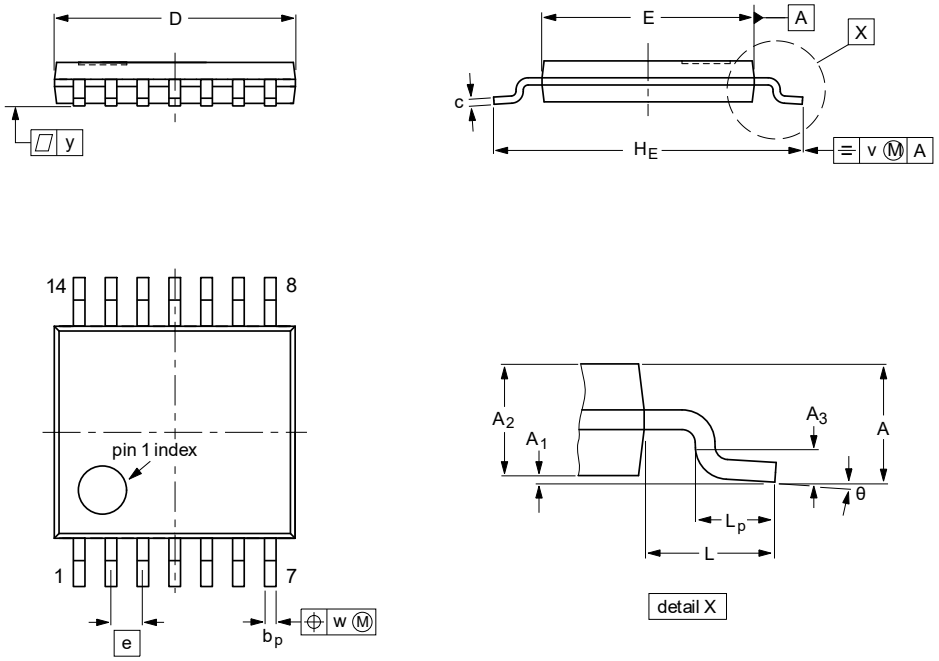
Note
1. Plastic or metal protrusions of 0.15 mm (0.006 inch) maximum per side are not included.

sot108-1_po

Outline version	References				European projection	Issue date
	IEC	JEDEC	JEITA			
SOT108-1		MS-012				~~03-02-19~~ 23-10-27

Fig. 19. Package outline SOT108-1 (SO14)

TSSOP14: plastic thin shrink small outline package; 14 leads; body width 4.4 mm **SOT402-1**



Dimensions (mm are the original dimensions)

Unit		A	A_1	A_2	A_3	b_p	c	$D^{(1)}$	$E^{(2)}$	e	H_E	L	L_p	v	w	y	θ
mm	max	1.20	0.15	1.05		0.30	0.2	5.1	4.5		6.6		0.75				8°
	nom				0.25					0.65		1		0.2	0.1	0.1	
	min		0.05	0.80		0.19	0.09	4.9	4.3		6.2		0.45				0°

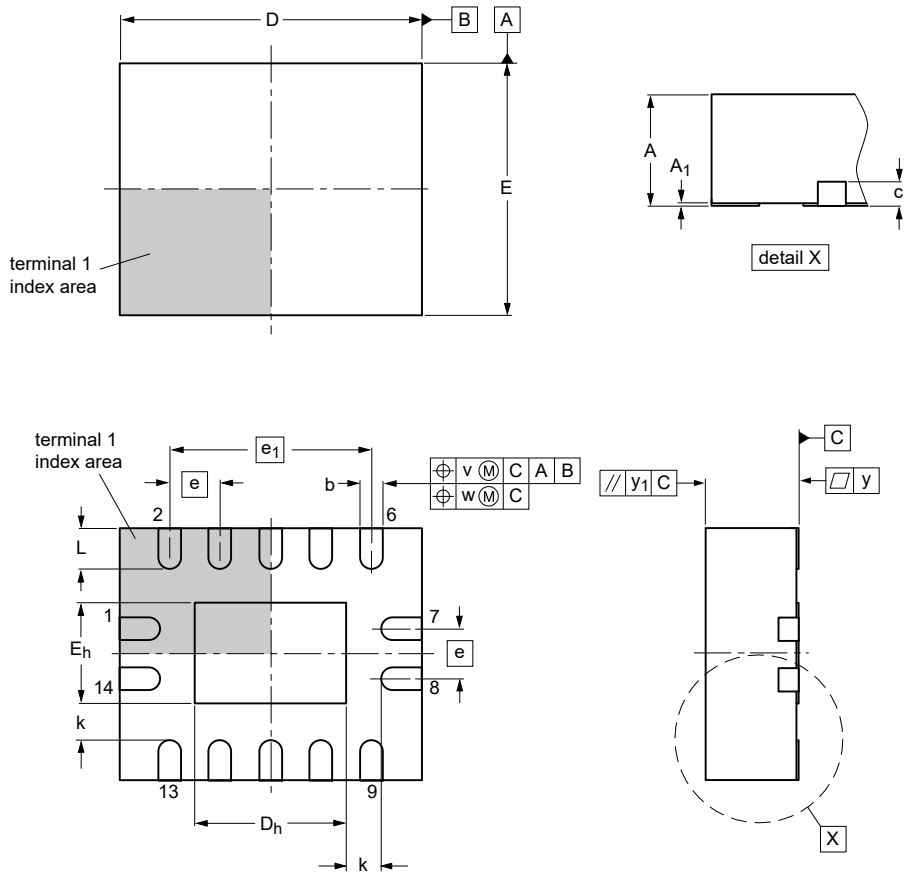
Note
1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

sot402-1_po

Outline version	References				European projection	Issue date
	IEC	JEDEC	JEITA			
SOT402-1		MO-153				~~03-02-18~~ 23-10-27

Fig. 20. Package outline SOT402-1 (TSSOP14)

DHVQFN14: plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 14 terminals; body 2.5 x 3 x 0.85 mm **SOT762-1**



Dimensions (mm are the original dimensions)

Unit		$A^{(1)}$	A_1	b	c	$D^{(1)}$	D_h	$E^{(1)}$	E_h	e	e_1	k	L	v	w	y	y_1
	max	1	0.05	0.30		3.1	1.65	2.6	1.15				0.5				
mm	nom		0.02	0.25	0.2	3.0	1.50	2.5	1.00	0.5	2		0.4	0.1	0.05	0.05	0.1
	min		0.00	0.18		2.9	1.35	2.4	0.85			0.2	0.3				

Note
1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

sot762-1_po

Outline version	References				European projection	Issue date
	IEC	JEDEC	JEITA			
SOT762-1		MO-241				~~15-04-10~~ 15-05-05

Fig. 21. Package outline SOT762-1 (DHVQFN14)

13. Abbreviations

Table 14. Abbreviations

Acronym	Description
CDM	Charged Device Model
CMOS	Complementary Metal-Oxide Semiconductor
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
TTL	Transistor-Transistor Logic

14. Revision history

Table 15. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74HC_HCT4066_Q100 v.5	20240321	Product data sheet	-	74HC_HCT4066_Q100 v.4
Modifications:	• Fig. 19, Fig. 20: Aligned SO and TSSOP package outline drawings to JEDEC MS-012 and MO-153. • Section 2: ESD specification updated according to the latest JEDEC standard.			
74HC_HCT4066_Q100 v.4	20200414	Product data sheet	-	74HC_HCT4066_Q100 v.3
Modifications:	• The format of this data sheet has been redesigned to comply with the identity guidelines of Nexperia. • Legal texts have been adapted to the new company name where appropriate. • Table 4: Derating values for P_{tot} total power dissipation have been updated. • Table 9: C_{PD} value of 74HC4066-Q100 moved to typical column. • Package outline drawing of SOT762-1 (Fig. 21) updated.			
74HC_HCT4066_Q100 v.3	20131216	Product data sheet	-	74HC_HCT4066_Q100 v.2
Modifications:	• Features and benefits updated (errata).			
74HC_HCT4066_Q100 v.2	20130404	Product data sheet	-	74HC_HCT4066_Q100 v.1
Modifications:	• Descriptive title corrected (errata). • New general description (errata).			
74HC_HCT4066_Q100 v.1	20120712	Product data sheet	-	-

15. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.
[2] The term 'short data sheet' is explained in section "Definitions".
[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the internet at https://www.nexperia.com.

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Date of release: 21 March 2024